



## Structural-physical material data:

Volume weight Surface Brinell hardness Tensile bond strength Value of the thermal conductivity  $\lambda_R$ Base value of the floor heating is  $\lambda_{10}$ Water vapor diffusion resistance rate  $\mu$ Specific thermal capacity c Coefficient of thermal expansion  $\alpha$ Elongation at temperature change Elongation at change of relative humidity at 20°C by 30% Hygrothermal assembly conditions (on site) ≥ 1500 kg/m<sup>3</sup>
≥ 40 N/mm<sup>2</sup>
≥ 1,0 N/mm<sup>2</sup>
0,44 W/(mK)
0,30 W/(mK)
30 / 50
> 1000 J/(kgK)
12,9\*10<sup>-6</sup> 1/K
≤ 0,02 mm/(mK)
0,6 mm/m

min. +13°C approx. 40-65% r. h. 20°C ±5°C approx. 40-65% r. h.

## Surface treatment and floor coverings

Cut floor covering always according to the expansion and connection joints of the Combi T.

Chair castor resistance is given for all MERO Combi T floors without additional procedures.

Primers, putties and adhesives must fit together with the system related fleeces and cloths. It is recommended to demand an installation guideline of the intended gluing system from the manufacturer.

<u>Textile coverings</u> (depending on the type of carpet) can be laid without putting the whole area, joint areas may be have to be leveled.

Elastic coverings (e.g. PVC, Linoleum, Rubber) usually require a whole area leveling of min. 2mm thickness.

<u>Ceramic tiles and natural stone coverings</u> can only be applied on approved systems. Should the allowed deflections due to the expected loads on the MERO Combi T be higher than the accepted deformations of the floor covering, additional measures have to considered. Ways to limit the deflection would be the use of thicker elements or additional pedestals. We would like to point out that depending on the covering and gluing type, the deflection can be reduced considerably. Project related tests are possible. Depending on tile size and installation method, flexible and fast curing adhesives may be necessary. Any moisture ingress to the carrier panel due to air humidity, sealants, mortars, etc. must be avoided. We recommend to use reaction based gluing systems and a moisture barrier to the bottom side of the panel (e.g. laminated aluminum foil).

<u>Parquet</u> to be executed as floating parquet or parquet  $\leq 2/3$  of the carrier panel thickness. Stave parquet or solid floorboards need to be considered separately. The use of grain-cut timber parquet is not recommended.

<u>Liquid coatings</u> must be elasticized. Always aim for a max. deflection of 0,5 mm at 600 mm pedestal grid. Consider the structural and physical conditions before choosing the coating system. We recommend to use a moisture barrier to the bottom side of the panel (e.g. laminated aluminum foil).